

Sheet 1 of 1							
FORM PTO 1449 (modified) U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE LIST OF REFERENCES CITED BY APPLICANT(S) (Use several sheets if necessary) Date Submitted to PTO: September 17, 2003				ATTY DOCKET NO. 2003_1338		SERIAL NO. NEW 10/664,078	
APPLICANT Mizuki NAGAI et al.				FILING DATE September 17, 2003			
U.S. PATENT DOCUMENTS							
*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
CW	AA	5,695,810	12/1997	Dubin et al.	427	96	
	AB	6,110,011	8/2000	Somekh et al.	451	28	
	AC	6,197,181	3/2001	Chen	205	123	
	AD	2002-0004301	1/2002	Chen et al.	438	687	
	AE	6,267,853	7/2001	Dordi et al.	204	232	
	AF	6,413,436	7/2002	Aegerter et al.	216	13	
	AG	6,350,364	2/2002	Jang	205	118	
	AH	6,319,387	11/2001	Krishnamoorthy et al.	205	240	
	AI	6,251,235	6/2001	Talieh et al.	204	220	
		2002-0033340	3/2002	Cheung et al.	205	101	
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO
CW	AJ	00/32835	6/2000	WIPO	—	—	
	AK			/			
	AL						
	AM						
OTHER DOCUMENT(S) (Including Author, Title, Date, Pertinent Pages, Etc.)							
CW	AO	Akihisa HONGO et al., "WAFER CLEANING APPARATUS", U.S. Patent Application Serial No. 09/572,432, filed May 17, 2000. <u>USP 6,615,854</u>					
CW	AP	Matsushita, Shinji, "Copper Electroplating Apparatus 'PARAGON' of Semitool, Loaded with Seed Layer Measuring Function, Seed Layer Strengthening/Repair Function", and, "Process Single Wafer Measuring Function", Semiconductor FPD World, vol. 19(10), pp. 122-124, Pressjournal (2000). <u>no month</u>					
	AQ						
EXAMINER <u>Edna Wong</u>					DATE CONSIDERED <u>1/6/05</u>		

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MP
 EP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.